FORM PTO-1449/A and B (Modified)	APPLICATION NO.: 09/940,073 ATTY. DOCKET NO.: H0498/7155
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Document

MAR 1 5 2002 **U.S. PATENT DOCUMENTS** Date of Publication or of issue **U.S. Patent Document** Cite Examiner's of Cited Document Kind No. Initials# MM-DD-YYYY Number Code 12/16/1997 38 5,698,485 **A1** Bruck et al. CF Baldus et al. 11/16/1999 39 5,958,430 **A**1 CE 40 02/02/1999 5,866,705 **A**1 Jansen et al. CE 11/10/1998 41 5,834,388 **A**1 Baldus et al.

FOREIGN PATENT DOCUMENTS

Examiner's	Cite No.	Cite Foreign Patent Document		ment	Name of Patentee or Applicant of Cited Document	Date of Publication of	Translation
Initials#		Office/ Country	Number /	Kind Code	(not necessary)	Cited Document MM-DD-YYYY	(Y/N)
CF	42	WO	96/29629	A2	Whitesides et al.	09/26/1996	Yes
C/=	43	WO	98/34886	A1	Schueller et al.	08/13/1998	VCS
CF-	44	EP	0112721 🗸	A2	Layton et al.	12/21/1983	ves
CF	45	EP	0672765 ✓	A1	Reetz et al.	03/04/1995	ves
CF	46	EP	07237229 🗸		Haruo et al. (Abstract)	12/09/1995	yes

OTHER ART — NON PATENT LITERATURE DOCUMENTS

Examiner's	Cite	Include name of the author (in CAPITAL LETTERS) title of the article (when appropriate), title of the	Translation	
Initials#	No	item (book, magazine, journal, serial, symposium, catalog, etc.), date, relevant page(s), volume-issue	(Y/N)	
	,	number(s), publisher, city and/or country where published.		
	47 ✔	JUNGERMANN, Hardy et al., "Synthesis of an extremely stable ceramic in the system Si/B/C/N using 1-		
CF		(trichlorosilyl)-1-(dichloroboryl)ethane as a single-source precursor", Mat. Res. Innova Vol. 2, pp. 200-206		
		(1999)		
~ _	48 🗸	BALDUS, Hans-Peter et al., "Novel High-Performance ceramics-Amorphous Inorganic Networks from		
Œ		Molecular Precursors", Angew. Chem. Int. Ed. Engl. Vol. 36, pp. 328-343 (1997)		
~~	49	WEINMANN, Marku et al., "Synthesis and Thermal Behavior of Novel Si-B-C-N Ceramic Precursors", Chem.		
cr	/	Mater. Vol. 12, pp. 623-632 (2000)		
~	50	RIEDEL, Ralf et al., "A silicoboron carbonitride ceramic stable to 2,000 °C", Nature Vol. 382 pp. 796-798		
CF		(August 1996)		
	51 🗸	WIDEMAN, Thomas, "Synthesis, Characterization, and Ceramic Conversion Reactions of Borazine/Silazane		
CF		Copolymers: New Polymeric Precursors to SiNCB Ceramics", Chem. Mater. Vol. 7, pp. 2203-2212 (1995)		
	52			
CF		Science Vol. 285, pp. 699-703 (July 30, 1999)		
^ _	53 🌙	BALDUS, H.P. et al., "Properties of Amorphous SiBNC-Ceramic Fibres", Key Engineering Materials Vols.		
CF		127-131 pp. 177-184 (1997)		
1	54 J	LINAN, An et al., "Development of Injectable Polymer-Derived Ceramics for High Temperature Mems", IEEE		
CF_		Conference on Micro Electro Mechanical Systems (2000)		
	55/	FREIMUTH, Herbert et al., "Formation of Complex Ceramic Miniaturized Structures by Pyrolysis of		
CF		Poly(vinylsilazane)", J. Am. Ceram. Soc. Vol. 79(6) pp. 1457-65 (1996)		
,	56 √	KIM, Enoch et al., "Two- and Three-Dimensional Crystallization of Polymeric Microspheres by Micromolding		
CF		in Capillaries", Adv. Mater. Vol. 8, No. 3, pp. 245-247 (1996)		
	57	ST. JOHN, Pamela et al., "Microcontact printing and pattern transfer using trichlorosilanes on oxide substrates",		
CF		Appl. Phys. Lett. Vol. 68(7), pp. 1022-1024 (1996)		
_	58 √	KIM, Enoch et al., "Combining Patterned Self-Assembled Monolayers of Alkanethiolates on Gold with		
CF		Anisotropic Etching of Silicon to Generate Controlled Surface Morphologies", J. Electrochem. Soc. Vol. 142,		
		No. 2, pp. 628-633 (1995)		

FORM PTO-1449/A and B (Modified) APPLICATION NO.: 09/940,073 ATTY. DOCKET NO.: H0498/7155 INFORMATION DISCLOSURE STATEMENT BY APPLICANT FILING DATE: August 27, 2001 JAN APPLICANT: Yang et al. JAN 0 3 2002 EXAMINER: Not-Yet Assigned GROUP ART UNIT:- 1732 Sheet of TE TRADEN FORILLA

U.S. PATENT DOCUMENTS

Examiner's Initials#	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited	Date of Publication or of issue	
		Number	Kind Code	Document	of Cited Document MM-DD-YYYY	
CF	1	3,900,614		Lando	08/19/1975	
CF	2	3,873,360	1	Lando	03/25/1975	
CF	3	3,873,359		Lando	03/25/1975	
CF	4	4,073,981		Baron	02/14/1978	
CF	5	4,098,922		Dinella et al.	07/04/1978	
CF	6	4,192,764		Madsen	03/11/1980	
CF	7	4,258,001		Pierce et al.	03/24/1981	
CF	8	4,472,458		Sirinyan et al.	09/18/1984	
CF	9	4,508,755		Reintjes et al.	04/02/1985	
CF	10	4,555,414		Hoover et al.	11/26/1985	
CF	11	4,687,657		Clark et al.	08/18/1987	
CF=	12	4,690,715		Clark et al. Allara et al. Bolt Takeda et al.	09/01/1987	
Œ	13	4,764,489		Bolt	08/16/1988	
CF	14	4,896,854		Takeda et al.	08/16/1988 09/26/1989	
CF	15	4,959,252		Takeda et al. Bonnebat et al.	09/25/1990	
CF-	16	5,073,495		Anderson	12/17/1991	
CF	17	5,079,600		Schnur et al.	01/07/1992	
CF	18	5,087,510	A1	Tokas et al.	02/11/1992	
CF	19	5,141,785	A1	Yoshinada et al.	08/25/1992	
CF	20	5,170,461	A1	Yoon et al.	12/08/1992	
CF	21	5,227,474	A1	Johnson et al.	07/13/1993	
CF	22	5,210,058	A1	Takeda et al.	05/11/1993	
CF	23	5,252,684	A1	Zank et al.	10/12/1993	
cF	24	5,259,926	A1	Kuwabara et al.	11/09/1993	
단	25	5,296,418	A1	Takeda et al.	03/22/1994	
CF	26	5,312,942	A1	Jansen	05/17/1994	
CF	27	5,345,869	A1	Treverton et al.	09/13/1994	
CF	28	5,385,116	A1	Hattori et al.	01/31/1995	
CF	29	5,386,006	A1	Masumoto et al.	01/31/1995	
5	30	5,405,982	A1	Loffelholz	04/11/1995	
CF	31	5,543,485	A1	Baldus	08/06/1996	
CF	32	5,439,829	A1	Anderson et al.	08/08/1995	
CF-	33	5,453,527	A1	Baldus et al.	09/26/1995	
CF	34	5,471,455	A1	Jabr	11/28/1995	
CF	35	5,484,324	A1	Okabayashi et al.	01/16/1996	
CF	36	5,512,131	A1	Kumar et al.	04/30/1996	
CF	37	5,620,850	A1	Bamdad et al.	04/15/1997	

FORM PTO-1449/A and B (Modified)	APPLICATION NO.: 09/940,073 ATTY. DOCKET NO.: H0498/7155
INFORMATION DISCLESURE STATEMENT BY APPLICANT	FILING DATE: August 27, 2001
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Sheet 3 of	GROUP ART UNIT: 1732 EXAMINER: Not Yet Assigned FIORILLA
Evaminar's Cita Include some of the city	NON PATENT LITERATURE DOCUMENTS

Examiner's	Cite	Include name of the author (in CAPITAL LETTERS) title of the article (when appropriate), title of the	Translation	
Initials#	No	item (book, magazine, journal, serial, symposium, catalog, etc.), date, relevant page(s), volume-issue	(Y/N)	
		number(s), publisher, city and/or country where published	(1/14)	
100	59 V	HAVERKORN VAN RIJSEWIJK, H.C. et al., "Manufacture of LaserVision video discs by a	- 1	
CF		photopolymerization process", Philips Tech. Rev. Vol. 40, No. 10, pp. 287-297 (1982)		
05	60 s	EMMELIUS, Michael et al., "Materials for Optical Data Storage", Angew. Chem. Int. Ed. Engl., Vol. 28, No. 11		
CF	L	/ pp. 1445-1471 (1989)		
CF	61√	LENZMANN, F. et al., "Thin-Film Micropatterning Using Polymer Microspheres", Chem. Mater., Vol. 6, pp.		
L C	L/	, 130-139 (1994)]	
OCF	62 🎸			
O CF		J. pp. 3114 - 3110 (1993)		
Wes		DUSHKIN, C.D., "Colored Multilayers from Transparent Submicrometer Spheres", Langmuir, Vol. 9, pp. 3695-		
> 08	\preceq	3701 (1993)		
- C.S.	P	HAYASHI, Sadao et al., "Imaging by Polystyrene Latex Particles", Journal of Colloid and Interface Science,		
	17	Vol. 144, No. 2, pp. 538-547 (1991)		
() H	105	XIA, Younan et al., "Microcontact Printing of Octadecylsiloxane on the Surface of Silicon Dioxide and Its		
		Application in Microfabrication", J. Am. Chem. Soc., Vol. 117, No. 37, pp. 9576-9577 (1995)		
HOE W	(a)	DIJKSMAN, J.F., "Analysis of the injection-moulding process", Philips Tech. Rev., Vol. 44, No. 7, pp. 212-217		
U-∩∑		(1989)		
	67 V		_	
CF.	-60	(1993)		
CF	68 🇸) approachous of neutronical continuous of neutronical continuous		
•	-60 /	Reviews Libtech, Vol. 12, pp. 19-26 (1994)		
CF	69/	SUNDBERG, Steven A. et al., "Spatially-Addressable Immobilization of Macromolecules on Solid Supports", J.		
5	70/	Am. Chem. Soc., Vol. 117, pp. 12050-12057 (1995)		
CF	70 /	1		
\sim	71 /	Assembled Monolayer: A Route to All-Organic Circuits", Chem. Mater., Vol. 7, pp. 526-529 (1995)		
CF	71 🗸	i solution in the structures formed by moditing in capitalities, wature, vol. 3/6 nn 3x1-3x4		
	72 J	(1995)		
CF	12 5	The state of the s		
l l	73 🗸	[Mater., Vol. 0, No. 7/8, pp. 000-004 (1994)		
CF	13 🗸	1 Applications in Materials Science Languages		
_ 4	74 /	Vol. 10, pp. 1498-1511 (1994)		
CF	/4 3	PRITCHARD, et al., "Micron-Scale Patterning of Biological Molecules", Communications, Angew. Chem. Int.		
į.	75 /	Ed. Engl., Vol. 34, No. 1, pp. 91-93 (1995)		
CF	15 /	POTOCHNIK, Stephen J. et al., "Selective Copper Chemical Vapor Deposition Using Pd-Activated		
	76	Organosilane Films", Langmuir, Vol. 11, No. 6, pp. 1841-1845 (1995)		
CF	70 •	DRESSICK, Walter J. et al., "Patterning of Self-Assembled Films Using Lithographic Exposure Tools", Jpn. J. Appl. Phys., Vol. 32, pp. 5829-5839 (1993)		
	77 🏑	LAZAROV General "Formation of Two dimensional Control of the Control of Two dimensional Control of the Control		
CF.	.,,			
	78	Fluorinated Oil Substrate", J. Chem. Soc. Faraday Trans., Vol. 90, No. 14, pp. 2077-2083 (1994) NAGAYAMA Kunjaki "Fabrication of Two Dimensional Colleged Agrees", Phys. Lett. 10, 100 (1994)		
CF		NAGAYAMA, Kuniaki, "Fabrication of Two-Dimensional Colloidal Arrays", <i>Phase Transitions</i> , Vol. 45, pp. 185-203 (1993)		
	79 /	HOYER, Patrick et al., "Small quantum-sized CdS particles assembled to form a regularly nanostructured		
CF	. , ,	porous film", Appl. Phys. Lett., Vol. 66, No. 20, pp. 2700-2702 (1995)		
<u> </u>	80			
0	- V	BONNEMANN, Helmut et al., "Preparation and Catalytic Properties of NR ⁺ ₄ -Stabilized Palladium Colloids*",		
CF		Applied Organometallic Chemistry, Vol. 8, pp. 361-377 (1994)		
1	81	REETZ, Manfred T. et al., "Size-Selective Synthesis of Nanostructured Transition Metal Clusters" 1.4m		
CF	/	Chem. Soc., Vol. 116, pp. 7401-7402 (1994)		
	82 J	REETZ, Manfred T. et al., "Visualization of Surfactants on Nanostructured Palladium Clusters by a		
CF		Combination of STM and High-Resolution TEM", Science, Vol. 267, pp. 367-369 (1995)		

FORM PTO-1449/A and B (Modified)	APPLICATION NO.: 09/940,073 ATTY. DOCKET NO.: H0498/7155
INFORMATION DISCLOSURE	FILING DATE: August 27, 2001
STATEMENT BY APPLICANT S	APPLICANT: Yang et al.
Sheet 4 of	GROUP ART UNIT: 1732 EXAMINER: Not Yet Assigned FIOR ILL A

OTHER ART — NON PATENT LITERATURE DOCUMENTS

Initialist No Initialist No Initialist No Itien (book, magazine, journal, serial, symposium, catalog, etc.), date, relevant page(s), volume-issue number(s), publisher, city and/or country where published. CF 83 MELDRUM, Fiona C. et al., "Fornation of Thin Films of Platinum, Palladium, and Mixed Platinum: Palladium Nanocrystallities by the Langmuir Monolayer Technique", Chem. Mater., Vol. 7, pp. 1112-1116 (1995) CF 84 VARGO, Terence G. et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates", Science, Vol. 262, pp. 1711-1712 (1993) CF 85 CALVERT, Jeffrey M. et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography", J. Yac. Sci. Technol. B, Vol. 9, No. 6, pp. 3447-3450 (1991) CF 87 CF 88 VAN DER PUTTEN, Andre M.T. et al., "Electroless Con for VLSI", MRS Bulletin, pp. 18-21 (June 1993) 87 CF 87 TINO, Chiu H. et al., "Selective Electrochemistry of Colloidal Palladium", J. Electrochem. Soc., Vol. 139, No. 12, pp. 3475-3480 (1992) CF 90 JACKSON, Robert L., "Pd", "Polycarylic acid) This Plims as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation", J. Electrochem. Soc., Vol. 137, No. 1, pp. 95-101 (1990) CF 91 VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 94 MAK, Celia Y., "Electroless Copper Deposition on Metals and Metal Silicides", MRS Bulletin, pp. 55-62 Valugus 1994) ABAR, Celia Y., "Electroless Copper Deposition on Metals and Metal Silicides", MRS Bulletin, pp. 55-62 Valugus 1994) Pattern Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nomplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) CF 98 VIAM ABORNANA, CEEN, Special Report, "Combinatorial chemistry spa	Examiner's	Cite	Include name of the author (in CAPITAL LETTERS) title of the article (when appropriate), title of the		
MELDRUM, Fiona C. et al., "Formation of Thin Films of Palatinum, and Mixed Platinum: Palladium Nanocrystallites by the Langmuir Monolayer Technique", *Chem. Mater., Vol. 7, pp. 1112-1116 (1995) CF 84 VARGO, Terrence G. et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates", *Science, Vol. 262, pp. 1711-1712 (1993) CF 85 CALVERT, Jeffrey M. et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography", *J. *Vac. Sci. Technol. B, Vol. 9, No. 6, pp. 3447-3450 (1991) CF 86 V LI, Jian et al., "Copper-Based Metallization for ULSI Applications", *MRS Bulletin, pp. 18-21 (June 1993) CF 87 V CHO, James S. H. et al., "Electroless Cu for VLSI", *MRS Bulletin, pp. 31-38 (June 1993) CF 87 V CHO, James S. H. et al., "Electroless Cu for VLSI", *MRS Bulletin, pp. 31-38 (June 1993) CF 89 TING, Chiu H. et al., "Selective Electroless Metal Deposition for Integrated Circuit Fabrication", *J. Electrochem. Soc., Vol. 139, No. 12, pp. 3475-3480 (1992) CF 90 JACKSON, Robert L., "Pd*/Poly(acrylic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation", *J. Electrochem. Soc., Vol. 130, No. 2, pp. 456-462 (1989) CF 91 VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Nickel", *J. Electrochem. Soc., Vol. 140, No. 8, pp. 2239-2235 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Copper Deposition: Electrochem. Soc., Vol. 140, No. 8, pp. 2236-2237 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", *J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) GF 94 MAKA, Colia v., "Electroless Copper Deposition on Metals and Metal Silicides", *MRS Bulletin, pp. 55-62 (August 1994) CF 95 DRESSICK, Walter J. et al., "Photopatterning and Selective Electroless Copper Depositis", *Annu. Rev. Mater. Sci., Vol. 21, pp. 93-129 (1991) CF 96 UBBIN, Valery M., "Electroless Ni-P Deposition on Silicon with Pd Activation", *J. Electrochem. Soc., Vo	Initials#	1	item (book, magazine, journal, serial, symposium, catalog etc.) data relevant paga(s) volume issue	1	
CF 83 MELDRUM, Fiona C. et al., "Formation of Thin Films of Platinum, Palladium, and Mixed Platinum: Palladium Nanocrystallites by the Langmuir Monolayer Technique", Chem. Mater., Vol. 7, pp. 1112-1116 (1995)			number(s), publisher, city and/or country where published	(1/	N)
ARACOLYSIALITES by the Langmuir Monolayer Technique", Chem. Mater., Vol. 7, pp. 1112-1116 (1995) CF 84 VARGO, Terrence G. et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates", Science, Vol. 262, pp. 1711-1712 (1993) CF 85 CALVERT, Ieffrey M. et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography", J. Vac. Sci. Technol. B, Vol. 9, No. 6, pp. 3447-3450 (1991) CF 86 V. I., Jian et al., "Copper-Based Metallization for ULSI Applications", MRS Bulletin, pp. 18-21 (June 1993) CF 87 V. CHO, James SAI. et al., "Electroless Cu for VLSI", MRS Bulletin, pp. 31-38 (June 1993) CF 88 VAN DER PUTTEN, Andre M.T. et al., "Electrochemistry of Colloidal Palladium", J. Electrochem. Soc., Vol. 139, No. 12, pp. 3475-3480 (1992) CF 90 / JACKSON, Robert L., "Pat'Poly(acrytic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalysts Formation", J. Electrochem. Soc., Vol. 137, No. 1, pp. 95-101 (1990) CF 91 VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Nickel", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2229-2235 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2239-2255 (1993) CF 93 JACKSON, Robert L., "Initiation of Electroless Copper Plating Using Pd"/Poly(acrylic acid) Films", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 95 DRESSICK, Walter J. et al., "Photopatterning and Selective Electroless Metallization of Surface-Attached Ligands", Chem. Mater., Vol. 5, pp. 148-150 (1993) CF 96 VAKACHARA, S., "Microstructure and Mechanical Properties of Electroless Copper Depositis", Annu. Rev. Mater. Sci. Vol. 21, pp. 93-129 (1991) CF 97 JEON, Noo Li et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) CF 99 BUAM and BORMAN, C&EN, Special Report, "Combinatori	0	83 🗸	MELDRUM, Fiona C. et al., "Formation of Thin Films of Platinum, Palladium, and Mixed Platinum, Palladium,		
CF 84 VARGO, Terrence G. et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates", Science, Vol. 262, pp. 1711-1712 (1993) CF 85 CALVERT, Jeffrey M. et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography", J. Vac. Sci. Technol. B, Vol. 9, No. 6, pp. 3447-3450 (1991) CF 86 V. L. Jian et al., "Copper-Based Metallization for ULSI Applications", MRS Bulletin, pp. 18-21 (June 1993) CF 87 CHO, James S.H. et al., "Electroless Cu for VLSI", MRS Bulletin, pp. 31-38 (June 1993) CF 87 VAN DER PUTTEN, Andre M.T. et al., "Electrochemistry of Colloidal Palladium", J. Electrochem. Soc., Vol. 139, No. 12, pp. 3475-3480 (1992) CF 89 TING, Chiu H. et al., "Selective Electroless Metal Deposition for Integrated Circuit Fabrication", J. Electrochem. Soc., Vol. 136, No. 2, pp. 456-462 (1989) CF 90 JACKSON, Robert L., "Pd"/Toly(acrylic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation", J. Electrochem. Soc., Vol. 137, No. 1, pp. 95-101 (1990) CF 91 VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Nickel", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2229-2235 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 93 JACKSON, Robert L., "Initiation of Electroless Copper Plating Using Pd"/Poly(acrylic acid) Films", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 94 MAK, Celia Y., "Electroless Copper Deposition on Metals and Metal Silicides", MRS Bulletin, pp. 55-62 (August 1994) CF 95 DRESSICK, Walter J. et al., "Photopatterning and Selective Electroless Copper Depositis", Annu. Rev. Mater. Sci., Vol. 21, pp. 93-129 (1991) CF 96 JON, Noo Li et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Silicon with Pd Activation", J. Electrochem. Soc., Vol. 139, No. 5, pp. 1289-1294 (1992) CF 99 BUAM and BORMAN, C			Nanocrystallites by the Langmuir Monolayer Technique". Chem. Mater. Vol. 7 pp. 1112-1116 (1995)		
CF 85 CALVERT, Jeffrey M. et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography", J. Vac. Sci. Technol. B, Vol. 9, No. 6, pp. 3447-3450 (1991) CF 86 LI, Jian et al., "Copper-Based Metallization for U.SI Applications", MRS Bulletin, pp. 18-21 (June 1993) CHO, James S.H. et al., "Electroless Cu for VLSI", MRS Bulletin, pp. 31-38 (June 1993) CF 87 CHO, James S.H. et al., "Electroless Cu for VLSI", MRS Bulletin, pp. 31-38 (June 1993) CF 89 TING, Chiu H. et al., "Selective Electroless Metal Deposition for Integrated Circuit Fabrication", J. Electrochem. Soc., Vol. 136, No. 2, pp. 456-462 (1989) CF 90 JACKSON, Robert L., "Pd" 'Poly(acrylic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation", J. Electrochem. Soc., Vol. 137, No. 1, pp. 95-101 (1990) CF 91 VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Nickel", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2292-2235 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2297-2235 (1993) CF 92 VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 93 MAK, Celia Y., "Electroless Copper Deposition on Metals and Metal Silicides", MRS Bulletin, pp. 55-62 (August 1994) CF 95 VDRESSICK, Walter J. et al., "Photopatterning and Selective Electroless Metallization of Surface-Attached Ligands", Chem. Mater., Vol. 5, pp. 148-150 (1993) CF 96 NAKAHARA, S., "Microstructure and Mechanical Properties of Electroless Copper Deposits", Annu. Rev. Mater. Sci., Vol. 21, pp. 93-129 (1991) DEON, Noo Li et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) BUMM and BORMAN, C&EN, Special Report, "Combinatorial chemistry spawns new software systems		84 <	VARGO, Terrence G. et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates". Science, Vol.		 -
C.F. 86 bf Li, Jian et al., "Copper-Based Metallization for ULSI Applications", MRS Bulletin, pp. 18-21 (June 1993) C.F. 87 bf CHO, James S.H. et al., "Electroless Cu for VLSI", MRS Bulletin, pp. 31-38 (June 1993) R. 87 bf CHO, James S.H. et al., "Electroless Cu for VLSI", MRS Bulletin, pp. 31-38 (June 1993) R. 88 bf VAN DER PUTTEN, Andre M.T. et al., "Electrochemistry of Colloidal Palladium", J. Electrochem. Soc., Vol. 139, No. 12, pp. 3475-3480 (1992) C.F. 89 bf TING, Chiu H. et al., "Selective Electroless Metal Deposition for Integrated Circuit Fabrication", J. Electrochem. Soc., Vol. 136, No. 2, pp. 456-462 (1989) G.F. 90 bf JACKSON, Robert L., "Pd"/Poly(acrytic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation", J. Electrochem. Soc., Vol. 137, No. 1, pp. 95-101 (1990) C.F. 91 bf VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Nickel", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2279-2235 (1993) C.F. 92 bf VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) C.F. 93 JACKSON, Robert L., "Hinitiation of Electroless Copper Plating Using Pd"/Poly(acrytic acid) Films", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) C.F. 94 MAK, Celia Y., "Electroless Copper Deposition on Metals and Metal Silicides", MRS Bulletin, pp. 55-62 (August 1994) C.F. 95 J DRESSICK, Walter J. et al., "Photopatterming and Selective Electroless Copper Deposits", Annu. Rev. Mater. Sci., Vol. 21, pp. 93-129 (1991) C.F. 96 J NAKAHARA, S., "Microstructure and Mechanical Properties of Electroless Copper Deposits", Annu. Rev. Mater. Sci., Vol. 21, pp. 93-129 (1991) C.F. 97 JEDN, Noo Li et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) C.F. 98 J DUBIN, Valery M., "Electroless Ni-P Deposition on Silicon w	<u> </u>		202, pp. 1/11-1/12 (1993)		İ
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CF 139, No. 12, pp. 3475-3480 (1992)	CF		LI, Jian et al., "Copper-Based Metallization for ULSI Applications", MRS Bulletin, pp. 18-21 (June 1993)		
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### CF 90 JACKSON, Robert L., "pd" Poly(acrylic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation", J. Electrochem. Soc., Vol. 137, No. 1, pp. 95-101 (1990) VAN DER PUTTEN, Andre M.T., "Anisotropic Deposition of Electroless Nickel", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2229-2235 (1993) VAN DER PUTTEN, Andre M.T., "Controlled Mechanical Adhesion of Electroless Cu Patterns", J. Electrochem. Soc., Vol. 140, No. 8, pp. 2376-2377 (1993) CF 92		00 /	139, No. 12, pp. 3475-3480 (1992)		İ
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Particle Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) 98 \ DUBIN, Valery M., "Electroless Ni-P Deposition on Silicon with Pd Activation", J. Electrochem. Soc., Vol. 139, No. 5, pp. 1289-1294 (1992) BUAM and BORMAN, C&EN, Special Report, "Combinatorial chemists focus on small molecules, molecular recognition, and automation", pp. 28-54, February 12, 1996 THAYER, Ann, C&EN, Special Report, "Combinatorial chemistry becoming core technology at drug discovery companies", pp. 57-64 (1996) KREIEGER, James, C&EN, Special Report, "Combinatorial chemistry spawns new software systems to manage.	05	95 √	DRESSICK, Walter J. et al., "Photopatterning and Selective Electroless Metallization of Surface-Attached	2	\angle
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 JEON, Noo Li et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) DUBIN, Valery M., "Electroless Ni-P Deposition on Silicon with Pd Activation", J. Electrochem. Soc., Vol. 139, No. 5, pp. 1289-1294 (1992) BUAM and BORMAN, C&EN, Special Report, "Combinatorial chemists focus on small molecules, molecular recognition, and automation", pp. 28-54, February 12, 1996 THAYER, Ann, C&EN, Special Report, "Combinatorial chemistry becoming core technology at drug discovery companies", pp. 57-64 (1996) KREIEGER, James, C&EN, Special Report, "Combinatorial chemistry spawns new software systems to manage. 	CE	96 V	NAKAHARA, S., "Microstructure and Mechanical Properties of Electroless Copper Deposits", Annu. Rev.	_	
Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates", Langmuir, Vol. 11, pp. 3024-3026 (1995) 98 \(\) DUBIN, Valery M., "Electroless Ni-P Deposition on Silicon with Pd Activation", J. Electrochem. Soc., Vol. 139, No. 5, pp. 1289-1294 (1992) BUAM and BORMAN, C&EN, Special Report, "Combinatorial chemists focus on small molecules, molecular recognition, and automation", pp. 28-54, February 12, 1996 THAYER, Ann, C&EN, Special Report, "Combinatorial chemistry becoming core technology at drug discovery companies", pp. 57-64 (1996) KREIEGER, James, C&EN, Special Report, "Combinatorial chemistry spawns new software systems to manage	9	075/	Mater. Sci., Vol. 21, pp. 93-129 (1991)	,	
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